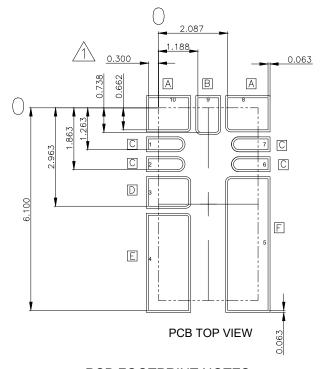
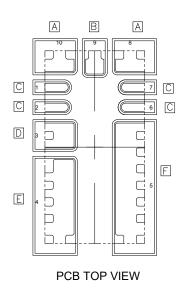
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PCB FOOTPRINT NOTES:

- 1. PADS TO EXTEND 0.30MM BEYOND COMPONENT EDGE.
- 2. ALL PADS ARE TO BE SOLDER MASK DEFINED (SMD), PCB FABRICATOR IS NOT TO OVERSIZE PAD OPENNINGS FOR THIS DEVICE.
- 3. SOLDER MASK AND SOLDER PASTE STENCIL OPENINGS SHOULD BE 1:1 WITH PADS SHOWN IN THE PAD DETAIL TABLE.
- 4. IT IS RECOMENDED THAT THE CONTRACT MANUFACTURER REVIEW AND OPTIMZE THE SOLDER PASTE STENCIL OPENINGS FOR THIS DEVICE. THE USE OF SEGMENTED STENCIL OPENINGS CAN HELP REDUCE SOLDER VOIDS AND PAD TO PAD SHORTS DUE TO EXCESSIVE SOLDER PASTE.

-DRAWING NOT TO SCALE-

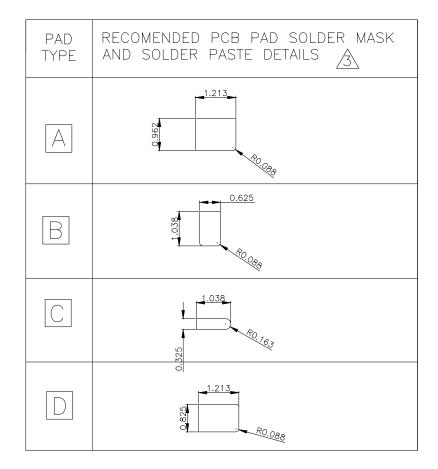
This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at http://www.maxim-ic.com/support for further questions.

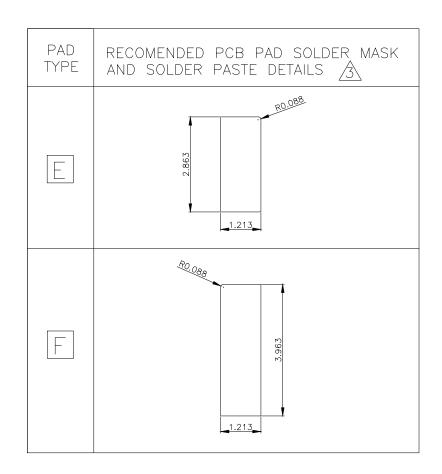


PACKAGE LAND PATTERN, [P105A3F-1] FCQFN

APPROVAL DOCUMENT CONTROL NO.

90-100039





NDTES:

- 1. REFERENCE PKG, DUTLINE: 21-100119
- 2. LAND PATTERN COMPLIES TO: IPC7351A.
- 3. TOLERANCE: +/- 0.02 MM.
- 4. ALL DIMENSIONS APPLY TO PEFREE (+) PKG, CODE ONLY.
- 5. ALL DIMENSIONS IN MM.
- 6. REFER TO APPLICATION NOTES 5963 FOR SMT STENCIL DESIGN RECOMMENDATIONS

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